

RAD-Plater

Equipped with Stir Cup
Compact lab use equipment



RAD-Plater Compact Lab Use Equipment

*RAD-Plater is best suited for via-filling, Sn/Ag solder, Cu pillar bump plating process. *Stir Cup enables to form high quality deposits.*

- Small and lightweight body
- Equipped with wheels for mobility
- For 2 to 8" wafers
- Capacity of 10 L or less plating solution
- Fast and easy setup with 100 V power & air
- Equipped with a circulation filter
- Improved maintainability by a chemical supply and drain pump.
- Features a interlock and other safety system
- Simple logic for simple operation

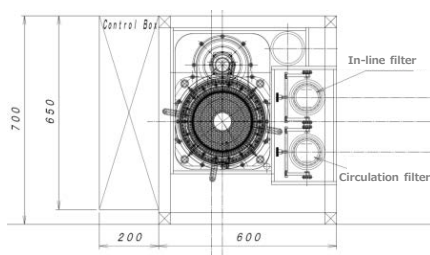
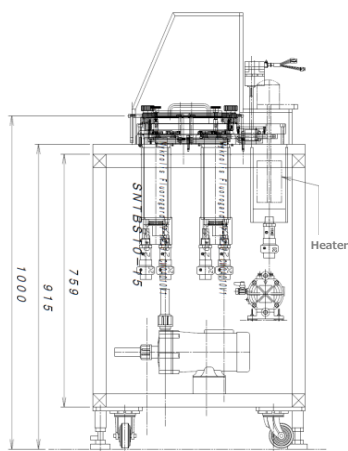


***Stir Cup**

Stir Cup improves thickness uniformity and air bubble removal performance in resist pattern by randomly stirring plating solution near the deposit area. Stir Cup achieves high speed plating at high current densities.

Specifications

Overall dimensions	W 0.8m x D 0.7m x H 1.5m
Plating cell	Stir Cup
wafers	2-8"
Plating solutions	10 L or less
Temperature range	25-65 °C
Heater	Teflon coated heater
Chiller	Optional (chiller unit)
Pump for Stir Cup	Magnet pump
Circulation pump	Magnet pump
Chemical supply & drain pump	Diaphragm pump
Circulation filter	3" cartridge
In-line filter	Optional (3" cartridge)
Rectifier	Optional (Equipped with a connection terminal)
Safety systems	Emergency stop button
	Overheat sensor/thermal fuse
	Liquid empty switch
Utilities	Leakage prevention pan
	Power: AC100V 15A (Outlet plug)
	Air: 0.5MPa (Rc1/4)
	Exhaust: 1m3/Hr (40A)
	N ₂ gas: optional (Rc1/4)



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OPlease note that product specifications are subject to change due to continual improvements.

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